



Statement of Materials, Construction

80L LQFP TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Ag Plated Cu	0.30900	Cu	7440-50-8	0.29404	43.40152	95.16
				Fe	7439-89-6	0.00062	0.09122	0.20
				Zn	7440-66-6	0.00056	0.08210	0.18
				Pb	7439-92-1	0.00015	0.02280	0.05
				Ni	7440-02-0	0.00989	1.45949	3.20
				Mn	7439-96-5	0.00031	0.04561	0.10
				Si	7440-21-3	0.00224	0.33067	0.73
				Silver (plating)	7440-22-4	0.00062	0.09122	0.20
2	Die	Silicon Chip	0.01000	Mg	7439-95-4	0.00054	0.07982	0.18
				Si	7440-21-3	0.00995	1.46864	99.50
3	Die Attach Material	Conductive Epoxy	0.00300	Epoxy Resin	Proprietary	0.00045	0.06642	15.00
				Silver	7440-22-4	0.00239	0.35203	79.50
				Aromatic Amine	Proprietary	0.00017	0.02435	5.50
4	Wire	Gold	0.00125	Au	7440-57-5	0.00125	0.18448	99.99
5	Lead Finish	Tin	0.04025	Sn	7440-31-5	0.04025	5.94068	100
6	Encapsulation	Epoxy Resin	0.31400	Fused Silica	60676-86-0	0.25654	37.86550	81.70
				Brominated Epoxy Resin	68541-56-0	0.00471	0.69521	1.50
				Carbon Black	1333-86-4	0.00094	0.13904	0.30
				Epoxy Resin	Proprietary	0.02355	3.47603	7.50
				Phenol Resin	Proprietary	0.02355	3.47603	7.50
				Antimony Trioxide	1309-64-4	0.00471	0.69521	1.50
Total Package Weight			0.67750					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%